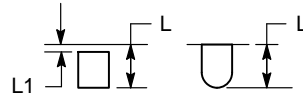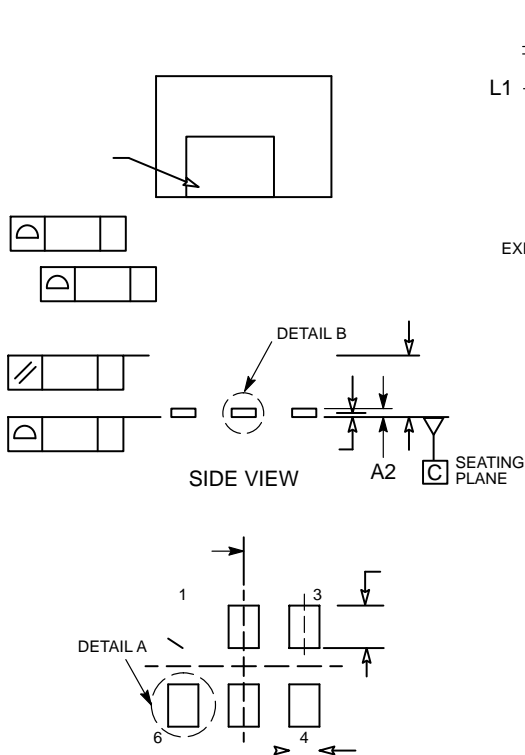**UDFN6, 1.45x1.0, 0.5P**
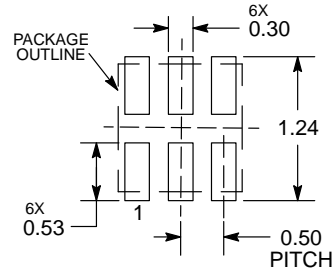**CASE 517AQ**
ISSUE O

SCALE 4:1

DATE 15 MAY 2008
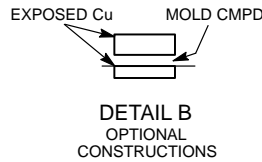
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

DETAIL A
OPTIONAL
CONSTRUCTIONS

EXPOSED Cu   MOLD CMPD

DETAIL B
OPTIONAL
CONSTRUCTIONS

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A2	0.07 REF	
b	0.20	0.30
D	1.45 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.30	0.40
L1	̈ ̈ ̈	0.15

DETAIL B

SIDE VIEW

A2   SEATING PLANE

MOUNTING FOOTPRINT

6X
0.30

PACKAGE
OUTLINE

1.24

6X
0.53

1

0.50
PITCH

DIMENSIONS: MILLIMETERS

DETAIL A

1   3

6   4

*For additional information on our Pb ïFree strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

**GENERIC
MARKING DIAGRAM***

XM

X   = Specific Device
Code
M   = Date Code
*This information is generic. Please refer to device data sheet for actual part marking. Pb ïFree indicator, "G" or microdot " ", may or may not be present.

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DESCRIPTION:	UDFN6, 1.45x1.0, 0.5P	PAGE 1 OF 1